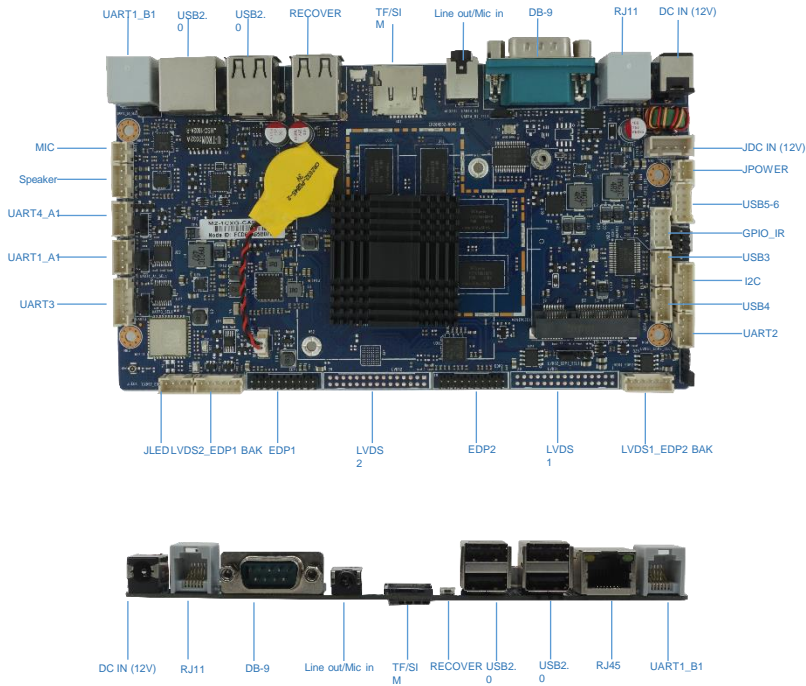


- RK3288W 4Core SOC , ARM Cortex-A17, Max. 1.6GHz
- Onboard 2GB DDR3L (optional 1GB)
- Supports dual display of LVDS1/LVDS2/EDP1/EDP2(option)
- Onboard 8GB EMMC (optional 16/32GB)
- 802.11b/g/n WIFI+BT
- 8 USB2.0, 3 COM
- 10/100M Etherne
- Supports GPIO/I2C/IR/RJ11/4G/Watchdog
- Supports 12V DC Input

Specification

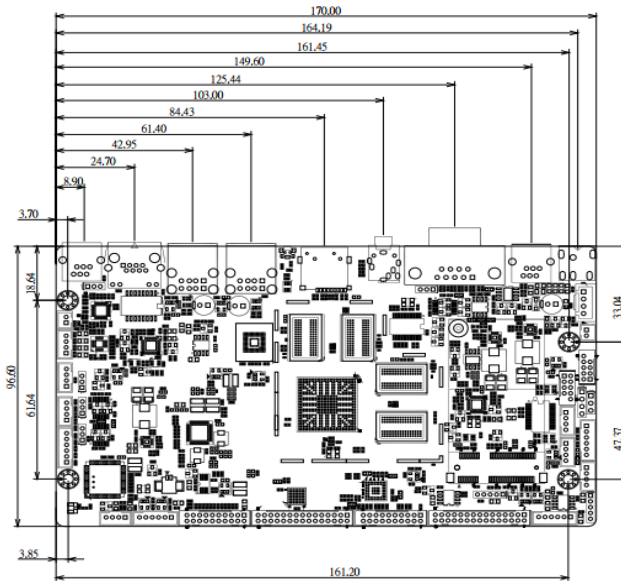
Processor	CPU	RK3288W 4Core SOC , ARM Cortex-A17, Max. 1.6GHz
	GPU	ARM Mali-400 MP4
Memory	Type	1GB/2GB DDR3L optional
System	OS	Android 7.1
Storage	Type	Onboard 8GB EMMC (optional 16/32GB)
Audio	Type	HD Audio IC, ALC5651
Network	LAN	1 x 10/100Mbps, RTL8201F
I/O	Displays	2 ,30 Pin, 2 x 15PIN LVDS Port 2 ,20 Pin, 2 x 10PIN eDP Port 1 x 6pin LVDS1_EDP2 BAK 1 x 6pin LVDS2_EDP1 BAK
	Audio interfaces	1 x 3.5mm Audio jack: Line out ,Mic in 1 x Mic in 2pin wafer Amplifier: 3W/4Ω x 2
	USB	IO: 4 USB2.0 Internal : 4 x USB2.0
	Serial	5 x COM (1个DB-9 option RS232/TTL/RS485, default RS232 , 3 x COM 4pin, RS232 option RS232/TTL, default RS232(UART1_A1,UART3,UART4_A1), 1个RJ11- 6pin) DB-9 (UART4_B1)与(UART4_A1)Co-lay RJ11-6PIN (UART1_B1) and UART1_A1 Co-lay Support 5/12V optional
	Expansion	1 x Mini PCIe for 3G/4G mobile network module 1 x SIM Slot,1 x TF Slot,1 x IR header 1 x TP-I2C(1 x 6pin 2.0mm wafer) 4 x GPIO header,1x JDC IN header 1x JPOWER header,1 x JLED header
Power	Input	12V DC input
Dimension	L X H	170mm x 96mm
Environment	Working temperature	-5~50°C
	Working Humidity	10%~90% non-condensing
	Storage temperture	-20~70°C
	Storage Humidity	5%~90% non-condensing

View



Size

IO



Information

P/N	Description
R28P-216LE	RK3288W/LVDS1/EDP1/8 USB2.0/3 COM/ 1 LAN
R28P-216EE	RK3288W/LVDS1/LVDS2/8 USB2.0/3 COM/ 1 LAN
R28P-216LL	RK3288W/LVDS1/LVDS2/8 USB2.0/3 COM/ 1 LAN

Product descriptions are subject to change without notice.